

Title (en)  
METHOD FOR REMOVING MATERIAL FROM A COMPONENT, AND ELECTRODE

Title (de)  
VERFAHREN ZUM ABTRAGEN VON MATERIAL VON EINEM BAUTEIL UND ELEKTRODE

Title (fr)  
PROCÉDÉ D'ENLÈVEMENT DE MATÉRIAU D'UN ÉLÉMENT ET ÉLECTRODE

Publication  
**EP 2237915 A2 20101013 (DE)**

Application  
**EP 08859567 A 20081205**

Priority  
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Abstract (en)  
[origin: CA2709195A1] In a method for removing material from a component (10, 10') that is connected as an anode, and wherein an electrode (12) that is connected as a cathode is guided to the component such that a gap (16) is formed, and wherein an electrolyte is introduced into the gap, a closed system is formed for the electrolyte by the formation of a duct. Said electrolyte is continuously guided from an inlet opening to an outlet opening of the duct. Forming the duct, e.g. by means of guide elements (18) that are mounted on the electrode (12), ensures that only those surface parts of the component (10) to be machined from which material is to be removed enter in contact with the electrode while the other surface parts do not enter in contact with the electrolyte. Since the electrolyte is continuously guided across said surface, used electrolyte is continuously discharged along with residual matter while fresh electrolyte is delivered such that the method can be carried out in a particularly trouble-free and expedient manner.

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